- 'LS377 and 'LS378 Contain Eight and Six Flip-Flops, Respectively, with Single-Rail Outputs
- 'LS379 Contains Four Flip-Flops with Double-Rail Outputs
- Individual Data Input to Each Flip-Flop
- Applications Include: Buffer/Storage Registers Shift Registers Pattern Generators

description

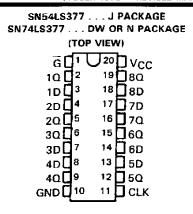
These monolithic, positive-edge-triggered flip-flops utilize TTL circuitry to implement D-type flip-flop logic with an enable input. The 'LS377, 'LS378, and 'LS379 devices are similar to 'LS273, 'LS174, and 'LS175, respectively, but feature a common enable instead of a common clear.

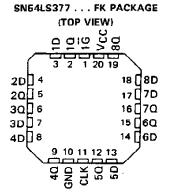
Information at the D inputs meeting the setup time requirements is transferred to the Q outputs on the positive-going edge of the clock pulse if the enable input \overline{G} is low. Clock triggering occurs at a particular voltage level and is not directly related to the transition time of the positive-going pulse. When the clock input is at either the high or low level, the D input signal has no effect at the output. The circuits are designed to prevent false clocking by transitions at the \overline{G} input.

These flip-flops are guaranteed to respond to clock frequencies ranging from 0 to 30 MHz while maximum clock frequency is typically 40 megahertz. Typical power dissipation is 10 milliwatts per flip-flop.

FUNCTION TABLE (EACH FLIP-FLOP)

	INPUT	S	OUTI	PUTS
G	CLOCK	DATA	a	ā
Н	х	Х	αo	αo
<u> </u> L	†	H	н	L
L	1	L	L	н
×	L	×	Q ₀	$\bar{\mathbf{Q}}_{0}$

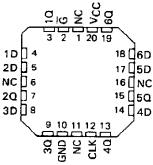




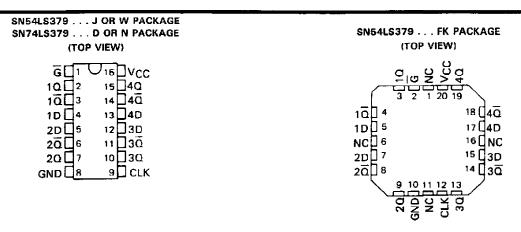
SN54LS378 . . . J OR W PACKAGE SN74LS378 . . . D OR N PACKAGE

(TOP VIEW) G [1 U16 [VCC 10 Q2 15 🗆 6Q 1D □3 14 🗆 6D 2D 🗆 4 13 0 5D 20.□5 12 5Q 3D 🛮 6 11 🗌 4D 30□7 10 40 9 CLK GND∐8

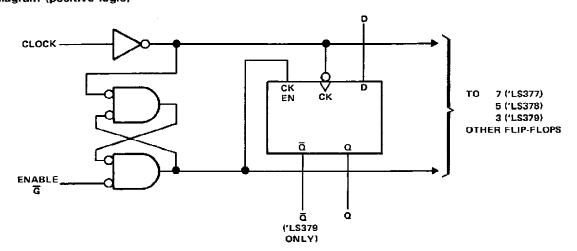
SN54LS378 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

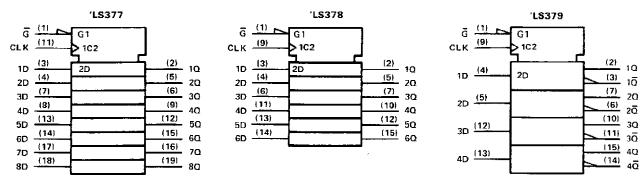


logic diagram (positive logic)



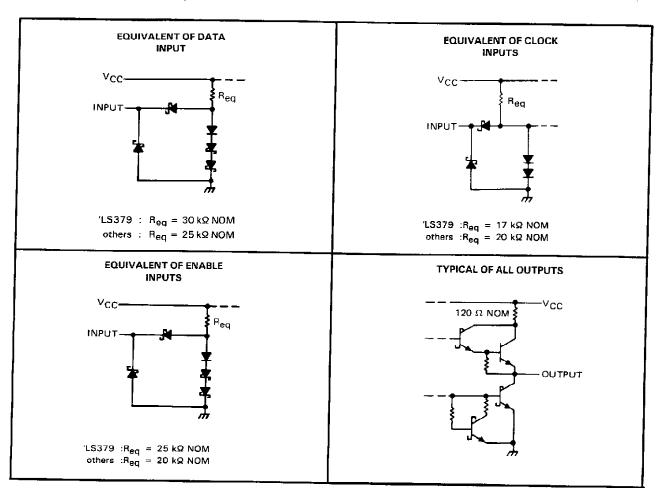
NC - No internal connection

logic symbols†



 $^{^\}dagger$ These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for DW, J, and N packages.

schematics of inputs and outputs



absolute maximum rating over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)						-					,								7 V
Input voltage	SN54LS								-	٠		•	-	•	-59	5°€	 Eto	. 12	7 V 25°C
Storage temperature range	SN74LS'	-					_	_				-				0°	'C t	o 7	0°C

NOTE 1: Voitage values are with respect to network ground terminal.

SN54LS377, SN54LS378, SN54LS379, SN74LS377, SN74LS378, SN74LS379 OCTAL, HEX, AND QUAD D-TYPE FLIP FLOPS WITH ENABLE

recommended operating conditions

			SN54L8	3′		Ī		
			NOM	MAX	MIN	NOM	MAX	דומט
Supply voltage, VCC		4.5	5	5.5	4.75	- 5	5.25	V
High-level output current, IOH				-400			-400	μΑ
Low-level output current, IOL				4			8	mΑ
Clock frequency, fclock		0		30	0		30	MHz
Width of clock pulse, tw		20			20			ns
	Data input	201			20↑			
Setup time, t _{SU}	Enable active-state	25↑			25↑			ns
	Enable inactive-state	101			10↑	-		''"
Hold time, th	Data and enable	5↑			5↑			ns
Operating free-air temperature, TA		-55		125	0		70	°C

 $^{^{\}dagger}$ The arrow indicates that the rising edge of the clock pulse is used for reference,

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS†				SN54LS	5'				
-		7201 301137110116				TYP‡	MAX	MIN	TYP‡	MAX	דומט
VIH	High-level input voltage				2			2			V
VIL	Low-level input voltage						0.7		-	0.8	V
VIK	Input clamp voltage	VCC = MIN,	II = -18 mA				-1,5			-1.5	
VoH	High-level output voltage	V _{CC} = MIN, V _{IL} = V _{IL} max,	V _{IH} = 2 V, I _{OH} = -400 μ/	1	2.5	3.5		2.7	3.5		v
VOL	Low-level output voltage	V _{CC} = MIN,	V _{IH} = 2 V,	I _{OL} = 4 mA		0.25	0,4		0.25	0.4 0.5	v
l _I	Input current at maximum input voltage	V _{CC} = MAX,	V _I = 7 V				0,1			0.1	mA
Iн	High-level input current	V _{CC} = MAX,	V _I = 2.7 V				20			20	μA
I _I L	Low-level input current	V _{CC} = MAX,	V _I = 0.4 V				-0,4			-0.4	mA
los	Short-circuit output current§	V _{CC} = MAX			-20		-100	-20		-100	mΑ
				'LS377	_	17	28		17	28	mΑ
ICC	Supply current	V _{CC} = MAX,	See Note 2	'LS378		13	22		13	22	mA
				'LS379		9	15		9	15	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, VCC = 5 V, $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
fmax	Maximum clock frequency	CL = 15 pF,	30	40		MHz
tPLH	Propagation delay time, low-to-high-level output from clock	R _L = 2 kΩ		17	27	ns
†PHL	Propagation delay time, high-to-low-level output from clock	See Note 3		18	27	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



[‡] All typical values are at V_{CC} = 5 V, T_A = 25°C. § Note more than one input should be shorted at a time, and duration of the short-circuit should not exceed one second.

NOTE 2: With all outputs open and ground applied to all data and enable inputs, ICC is measured after a momentary ground, then 4.5 V, is applied to clock.

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